

Title (en)

METHOD FOR A CHEMICAL AND/OR ELECTROLYTIC SURFACE TREATMENT OF A SUBSTRATE IN A PROCESS STATION

Title (de)

VERFAHREN ZUR CHEMISCHEN UND/ODER ELEKTROLYTISCHEN OBERFLÄCHENBEHANDLUNG EINES SUBSTRATS IN EINER PROZESSSTATION

Title (fr)

PROCÉDÉ POUR UN TRAITEMENT DE SURFACE CHIMIQUE ET/OU ÉLECTROLYTIQUE D'UN SUBSTRAT DANS UNE STATION DE TRAITEMENT

Publication

EP 3885474 A1 20210929 (EN)

Application

EP 20165608 A 20200325

Priority

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Abstract (en)

The invention relates to a method for a chemical and/or electrolytic surface treatment of a substrate in a process station and a process station for a chemical and/or electrolytic surface treatment of a substrate. The method for a chemical and/or electrolytic surface treatment comprises the following steps, not necessarily in this order: - mounting a substrate to be treated to a rotor unit, - moving the rotor unit with the substrate into a pre-wetting chamber of the process station, - applying a pre-wetting fluid to the substrate in the pre-wetting chamber, - moving the rotor unit with the substrate at least partially out of the pre-wetting chamber, - spinning the rotor unit with the substrate in a spinning plane to centrifugally reduce the pre-wetting fluid at a surface of the substrate, - rotating the rotor unit with the substrate normal to the spinning plane so that the substrate faces away from the pre-wetting chamber, - moving the rotor unit with the substrate into an electroplating chamber of the process station, - applying an electrolyte liquid and an electric current to the substrate for an electroplating process on the substrate in the electroplating chamber, and - moving the rotor unit with the substrate at least partially out of the electroplating chamber.

IPC 8 full level

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Citation (applicant)

US 2015179458 A1 20150625 - MAYER STEVEN T [US], et al

Citation (search report)

- [XD] US 2015179458 A1 20150625 - MAYER STEVEN T [US], et al
- [X] US 2004016637 A1 20040129 - YANG MICHAEL X [US], et al

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